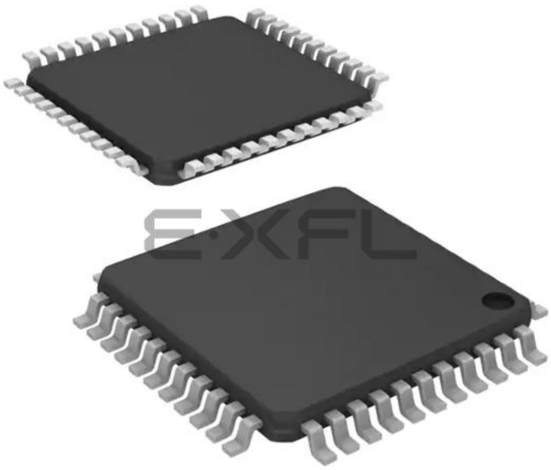

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32mc504-e-pt

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TABLE 4-23: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 1 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0400-041E	See definition when WIN = x																
C1BUFPNT1	0420	F3BP<3:0>				F2BP<3:0>				F1BP<3:0>				F0BP<3:0>				0000
C1BUFPNT2	0422	F7BP<3:0>				F6BP<3:0>				F5BP<3:0>				F4BP<3:0>				0000
C1BUFPNT3	0424	F11BP<3:0>				F10BP<3:0>				F9BP<3:0>				F8BP<3:0>				0000
C1BUFPNT4	0426	F15BP<3:0>				F14BP<3:0>				F13BP<3:0>				F12BP<3:0>				0000
C1RXM0SID	0430	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM0EID	0432	EID<15:8>								EID<7:0>								xxxx
C1RXM1SID	0434	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM1EID	0436	EID<15:8>								EID<7:0>								xxxx
C1RXM2SID	0438	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM2EID	043A	EID<15:8>								EID<7:0>								xxxx
C1RXF0SID	0440	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF0EID	0442	EID<15:8>								EID<7:0>								xxxx
C1RXF1SID	0444	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF1EID	0446	EID<15:8>								EID<7:0>								xxxx
C1RXF2SID	0448	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF2EID	044A	EID<15:8>								EID<7:0>								xxxx
C1RXF3SID	044C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF3EID	044E	EID<15:8>								EID<7:0>								xxxx
C1RXF4SID	0450	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF4EID	0452	EID<15:8>								EID<7:0>								xxxx
C1RXF5SID	0454	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF5EID	0456	EID<15:8>								EID<7:0>								xxxx
C1RXF6SID	0458	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF6EID	045A	EID<15:8>								EID<7:0>								xxxx
C1RXF7SID	045C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF7EID	045E	EID<15:8>								EID<7:0>								xxxx
C1RXF8SID	0460	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF8EID	0462	EID<15:8>								EID<7:0>								xxxx
C1RXF9SID	0464	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF9EID	0466	EID<15:8>								EID<7:0>								xxxx
C1RXF10SID	0468	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF10EID	046A	EID<15:8>								EID<7:0>								xxxx
C1RXF11SID	046C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

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4.5.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions, which apply to dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, and the DSP accumulator class of instructions, which apply to the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

Note:	For the `MOV` instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

Note:	Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.5.4 `MAC` INSTRUCTIONS (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X DEVICES ONLY)

The dual source operand DSP instructions (`CLR`, `ED`, `EDAC`, `MAC`, `MPY`, `MPY.N`, `MOVSAC` and `MSC`), also referred to as `MAC` instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the Data Pointers through register indirect tables.

The Two-Source Operand Prefetch registers must be members of the set: {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must therefore, be valid addresses within X Data Space for W8 and W9, and Y Data Space for W10 and W11.

Note:	Register Indirect with Register Offset Addressing mode is available only for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the `MAC` class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.5.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, `BRA` (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the `DISI` instruction uses a 14-bit unsigned literal field. In some instructions, such as `ULNK`, the source of an operand or result is implied by the opcode itself. Certain operations, such as a `NOP`, do not have any operands.

REGISTER 5-1: NVMCON: NONVOLATILE MEMORY (NVM) CONTROL REGISTER

R/SO-0(1)	R/W-0(1)	R/W-0(1)	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	NVMSIDL(2)	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0(1)	R/W-0(1)	R/W-0(1)	R/W-0(1)
—	—	—	—	NVMOP3(3,4)	NVMOP2(3,4)	NVMOP1(3,4)	NVMOP0(3,4)
bit 7							bit 0

Legend:	SO = Settable Only bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **WR:** Write Control bit(1)
- `1` = Initiates a Flash memory program or erase operation; the operation is self-timed and the bit is cleared by hardware once the operation is complete
- `0` = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit(1)
- `1` = Enables Flash program/erase operations
- `0` = Inhibits Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit(1)
- `1` = An improper program or erase sequence attempt or termination has occurred (bit is set automatically on any set attempt of the WR bit)
- `0` = The program or erase operation completed normally

bit 12 **NVMSIDL:** NVM Stop in Idle Control bit(2)
- `1` = Flash voltage regulator goes into Standby mode during Idle mode
- `0` = Flash voltage regulator is active during Idle mode

bit 11-4 **Unimplemented:** Read as ‘0’

bit 3-0 **NVMOP<3:0>:** NVM Operation Select bits(1,3,4)
- `1111` = Reserved
- `1110` = Reserved
- `1101` = Reserved
- `1100` = Reserved
- `1011` = Reserved
- `1010` = Reserved
- `0011` = Memory page erase operation
- `0010` = Reserved
- `0001` = Memory double-word program operation(5)
- `0000` = Reserved

Note 1: These bits can only be reset on a POR.
2: If this bit is set, there will be minimal power savings (I_{IDLE}) and upon exiting Idle mode, there is a delay (T_{VREG}) before Flash memory becomes operational.
3: All other combinations of NVMOP<3:0> are unimplemented.
4: Execution of the PWRSAV instruction is ignored while any of the NVM operations are in progress.
5: Two adjacent words on a 4-word boundary are programmed during execution of this operation.

REGISTER 7-7: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	ILR3	ILR2	ILR1	ILR0
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
VECNUM7	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits
1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7-0 **VECNUM<7:0>:** Vector Number of Pending Interrupt bits
11111111 = 255, Reserved; do not use
•
•
•
00001001 = 9, IC1 – Input Capture 1
00001000 = 8, INT0 – External Interrupt 0
00000111 = 7, Reserved; do not use
00000110 = 6, Generic soft error trap
00000101 = 5, DMAC error trap
00000100 = 4, Math error trap
00000011 = 3, Stack error trap
00000010 = 2, Generic hard trap
00000001 = 1, Address error trap
00000000 = 0, Oscillator fail trap

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10.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this cannot be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU Idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the ECAN™ module has been configured for 500 kbps, based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the ECAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

A peripheral module is enabled only if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note: If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

10.5 Power-Saving Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

10.5.1 KEY RESOURCES

- **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES

Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment
000 0000	I	Vss	010 1101	I	RPI45
000 0001	I	C1OUT[1]	010 1110	I	RPI46
000 0010	I	C2OUT[1]	010 1111	I	RPI47
000 0011	I	C3OUT[1]	011 0000	—	—
000 0100	I	C4OUT[1]	011 0001	—	—
000 0101	—	—	011 0010	—	—
000 0110	I	PTGO30[1]	011 0011	I	RPI51
000 0111	I	PTGO31[1]	011 0100	I	RPI52
000 1000	I	FINDX1[1,2]	011 0101	I	RPI53
000 1001	I	FHOME1[1,2]	011 0110	I/O	RP54
000 1010	—	—	011 0111	I/O	RP55
000 1011	—	—	011 1000	I/O	RP56
000 1100	—	—	011 1001	I/O	RP57
000 1101	—	—	011 1010	I	RPI58
000 1110	—	—	011 1011	—	—
000 1111	—	—	011 1100	—	—
001 0000	—	—	011 1101	—	—
001 0001	—	—	011 1110	—	—
001 0010	—	—	011 1111	—	—
001 0011	—	—	100 0000	—	—
001 0100	I/O	RP20	100 0001	—	—
001 0101	—	—	100 0010	—	—
001 0110	—	—	100 0011	—	—
001 0111	—	—	100 0100	—	—
001 1000	I	RPI24	100 0101	—	—
001 1001	I	RPI25	100 0110	—	—
001 1010	—	—	100 0111	—	—
001 1011	I	RPI27	100 1000	—	—
001 1100	I	RPI28	100 1001	—	—
001 1101	—	—	100 1010	—	—
001 1110	—	—	100 1011	—	—
001 1111	—	—	100 1100	—	—
010 0000	I	RPI32	100 1101	—	—
010 0001	I	RPI33	100 1110	—	—
010 0010	I	RPI34	100 1111	—	—
010 0011	I/O	RP35	101 0000	—	—
010 0100	I/O	RP36	101 0001	—	—
010 0101	I/O	RP37	101 0010	—	—
010 0110	I/O	RP38	101 0011	—	—
010 0111	I/O	RP39	101 0100	—	—

Legend: Shaded rows indicate PPS Input register values that are unimplemented.

Note 1: See **Section 11.4.4.1 "Virtual Connections"** for more information on selecting this pin assignment.

2: These inputs are available on dsPIC33EPXXXGP/MC50X devices only.

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REGISTER 11-15: RPINR37: PERIPHERAL PIN SELECT INPUT REGISTER 37 (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SYNCI1R<6:0>						
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **SYNCI1R<6:0>:** Assign PWM Synchronization Input 1 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to V_{SS}

bit 7-0 **Unimplemented:** Read as ‘0’

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REGISTER 11-18: RPOR0: PERIPHERAL PIN SELECT OUTPUT REGISTER 0

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP35R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP20R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP35R<5:0>:** Peripheral Output Function is Assigned to RP35 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP20R<5:0>:** Peripheral Output Function is Assigned to RP20 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 11-19: RPOR1: PERIPHERAL PIN SELECT OUTPUT REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP37R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP36R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP37R<5:0>:** Peripheral Output Function is Assigned to RP37 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP36R<5:0>:** Peripheral Output Function is Assigned to RP36 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 16-14: TRIGx: PWMx PRIMARY TRIGGER COMPARE VALUE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **TRGCMP<15:0>:** Trigger Control Value bits

When the primary PWMx functions in local time base, this register contains the compare values that can trigger the ADC module.

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FIGURE 25-4: USER-PROGRAMMABLE BLANKING FUNCTION BLOCK DIAGRAM

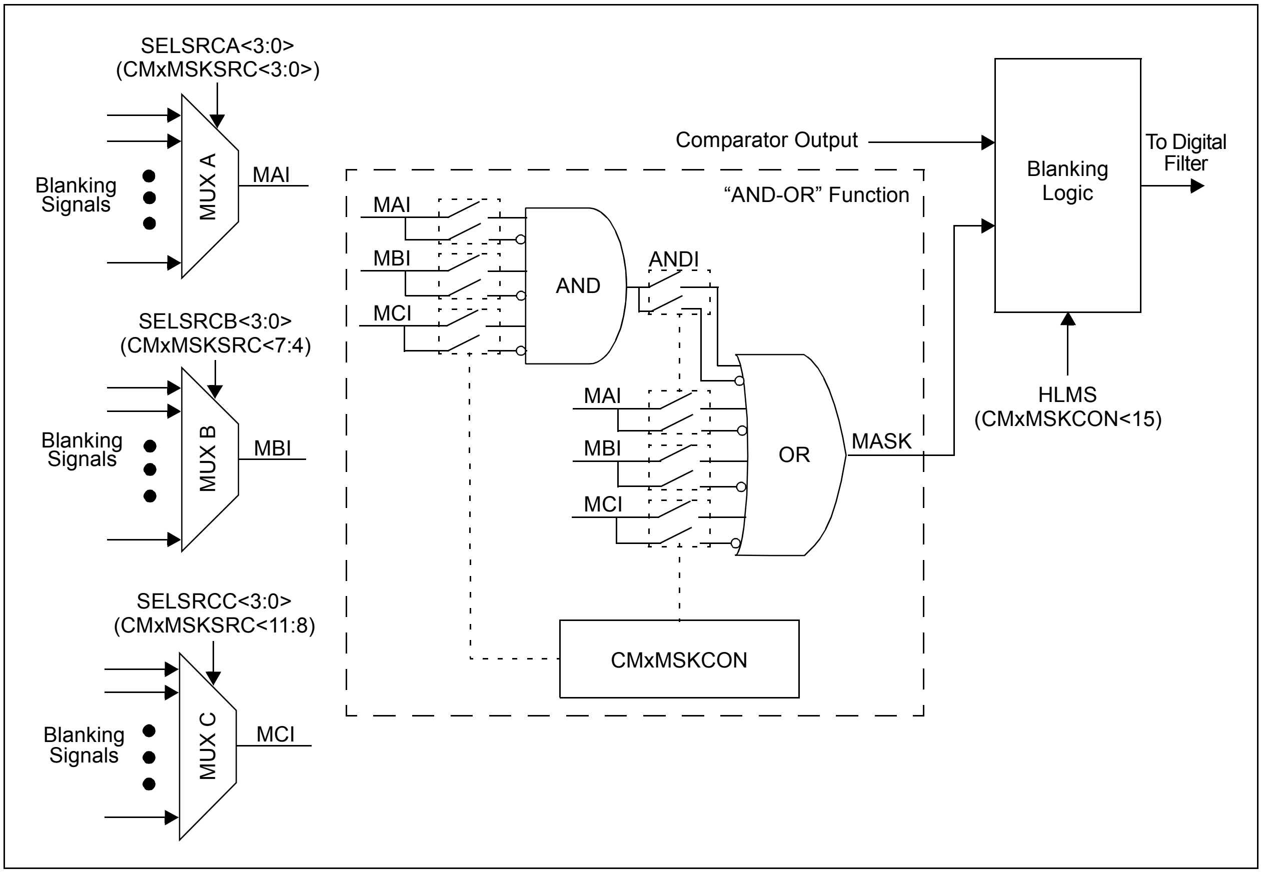
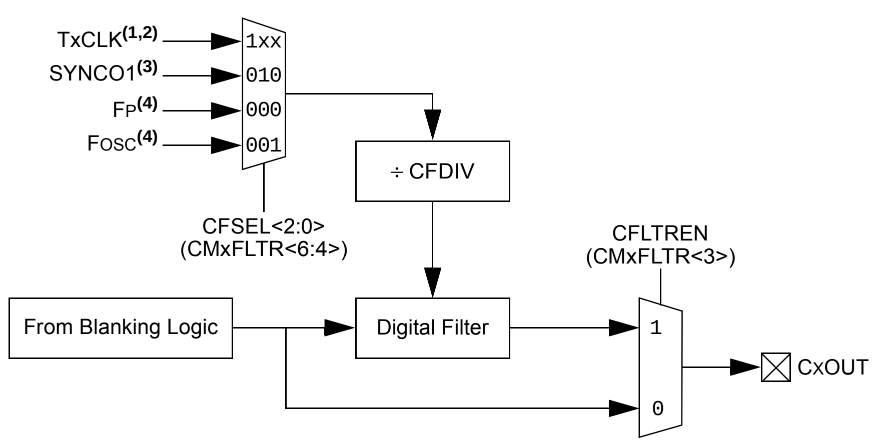


FIGURE 25-5: DIGITAL FILTER INTERCONNECT BLOCK DIAGRAM



Note 1: See the Type C Timer Block Diagram (Figure 13-2).
2: See the Type B Timer Block Diagram (Figure 13-1).
3: See the High-Speed PWMx Module Register Interconnection Diagram (Figure 16-2).
4: See the Oscillator System Diagram (Figure 9-1).

26.0 PROGRAMMABLE CYCLIC REDUNDANCY CHECK (CRC) GENERATOR

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Programmable Cyclic Redundancy Check (CRC)"** (DS70346) of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The programmable CRC generator offers the following features:

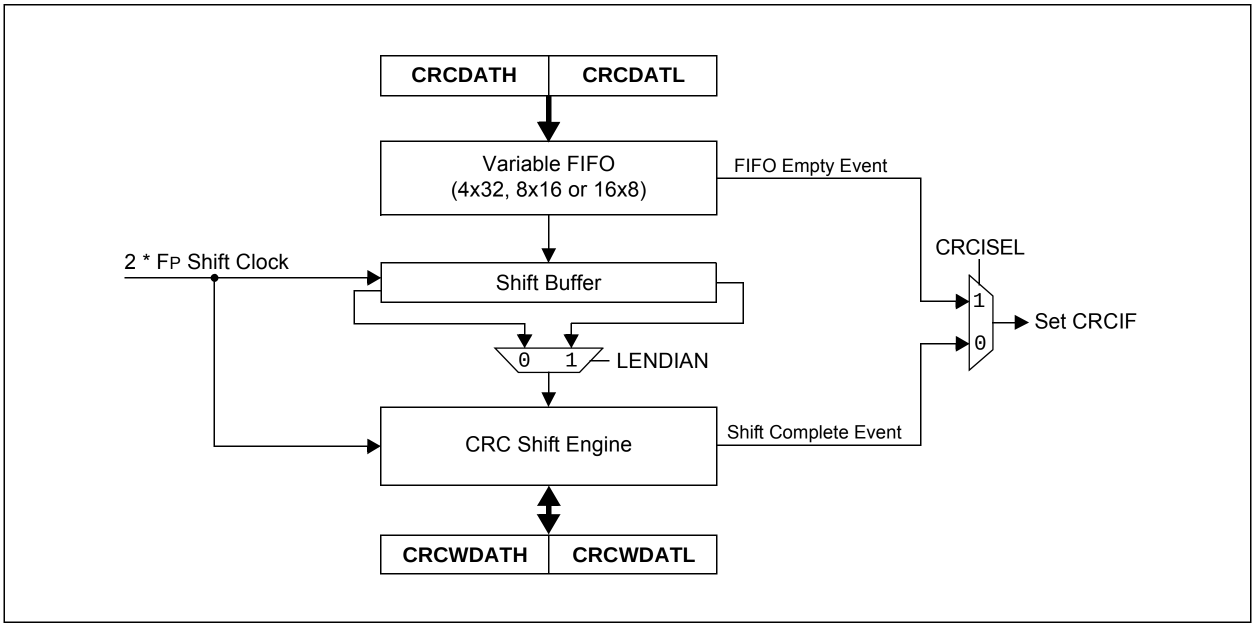
- User-programmable (up to 32nd order) polynomial CRC equation
- Interrupt output
- Data FIFO

The programmable CRC generator provides a hardware implemented method of quickly generating checksums for various networking and security applications. It offers the following features:

- User-programmable CRC polynomial equation, up to 32 bits
- Programmable shift direction (little or big-endian)
- Independent data and polynomial lengths
- Configurable interrupt output
- Data FIFO

A simplified block diagram of the CRC generator is shown in Figure 26-1. A simple version of the CRC shift engine is shown in Figure 26-2.

FIGURE 26-1: CRC BLOCK DIAGRAM



27.6 JTAG Interface

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement a JTAG interface, which supports boundary scan device testing. Detailed information on this interface is provided in future revisions of the document.

Note:	Refer to **"Programming and Diagnostics"** (DS70608) in the *"dsPIC33/PIC24 Family Reference Manual"* for further information on usage, configuration and operation of the JTAG interface.

27.7 In-Circuit Serial Programming

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can be serially programmed while in the end application circuit. This is done with two lines for clock and data, and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to the *"dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70663) for details about In-Circuit Serial Programming (ICSP).

Any of the three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

27.8 In-Circuit Debugger

When MPLAB® ICD 3 or REAL ICE™ is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB IDE. Debugging functionality is controlled through the PGECx (Emulation/Debug Clock) and PGEDx (Emulation/Debug Data) pin functions.

Any of the three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{\text{MCLR}}$, VDD, VSS and the PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins (PGECx and PGEDx).

27.9 Code Protection and CodeGuard™ Security

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X devices offer basic implementation of CodeGuard Security that supports only General Segment (GS) security. This feature helps protect individual Intellectual Property.

Note:	Refer to **"CodeGuard™ Security"** (DS70634) in the *"dsPIC33/PIC24 Family Reference Manual"* for further information on usage, configuration and operation of CodeGuard Security.

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30.1 DC Characteristics

TABLE 30-1: OPERATING MIPS VS. VOLTAGE

Characteristic	V_{DD} Range (in Volts)	Temp Range (in °C)	Maximum MIPS
			dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X
—	3.0V to 3.6V(1)	-40°C to +85°C	70
—	3.0V to 3.6V(1)	-40°C to +125°C	60

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typ.	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	T_J	-40	—	+125	°C
Operating Ambient Temperature Range	T_A	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	T_J	-40	—	+140	°C
Operating Ambient Temperature Range	T_A	-40	—	+125	°C
Power Dissipation: Internal chip power dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $I/O = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ.	Max.	Unit	Notes
Package Thermal Resistance, 64-Pin QFN	θ_{JA}	28.0	—	°C/W	1
Package Thermal Resistance, 64-Pin TQFP 10x10 mm	θ_{JA}	48.3	—	°C/W	1
Package Thermal Resistance, 48-Pin UQFN 6x6 mm	θ_{JA}	41	—	°C/W	1
Package Thermal Resistance, 44-Pin QFN	θ_{JA}	29.0	—	°C/W	1
Package Thermal Resistance, 44-Pin TQFP 10x10 mm	θ_{JA}	49.8	—	°C/W	1
Package Thermal Resistance, 44-Pin VTLA 6x6 mm	θ_{JA}	25.2	—	°C/W	1
Package Thermal Resistance, 36-Pin VTLA 5x5 mm	θ_{JA}	28.5	—	°C/W	1
Package Thermal Resistance, 28-Pin QFN-S	θ_{JA}	30.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SSOP	θ_{JA}	71.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SOIC	θ_{JA}	69.7	—	°C/W	1
Package Thermal Resistance, 28-Pin SPDIP	θ_{JA}	60.0	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θ_{JA}) numbers are achieved by package simulations.

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FIGURE 30-12: QEA/QEB INPUT CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

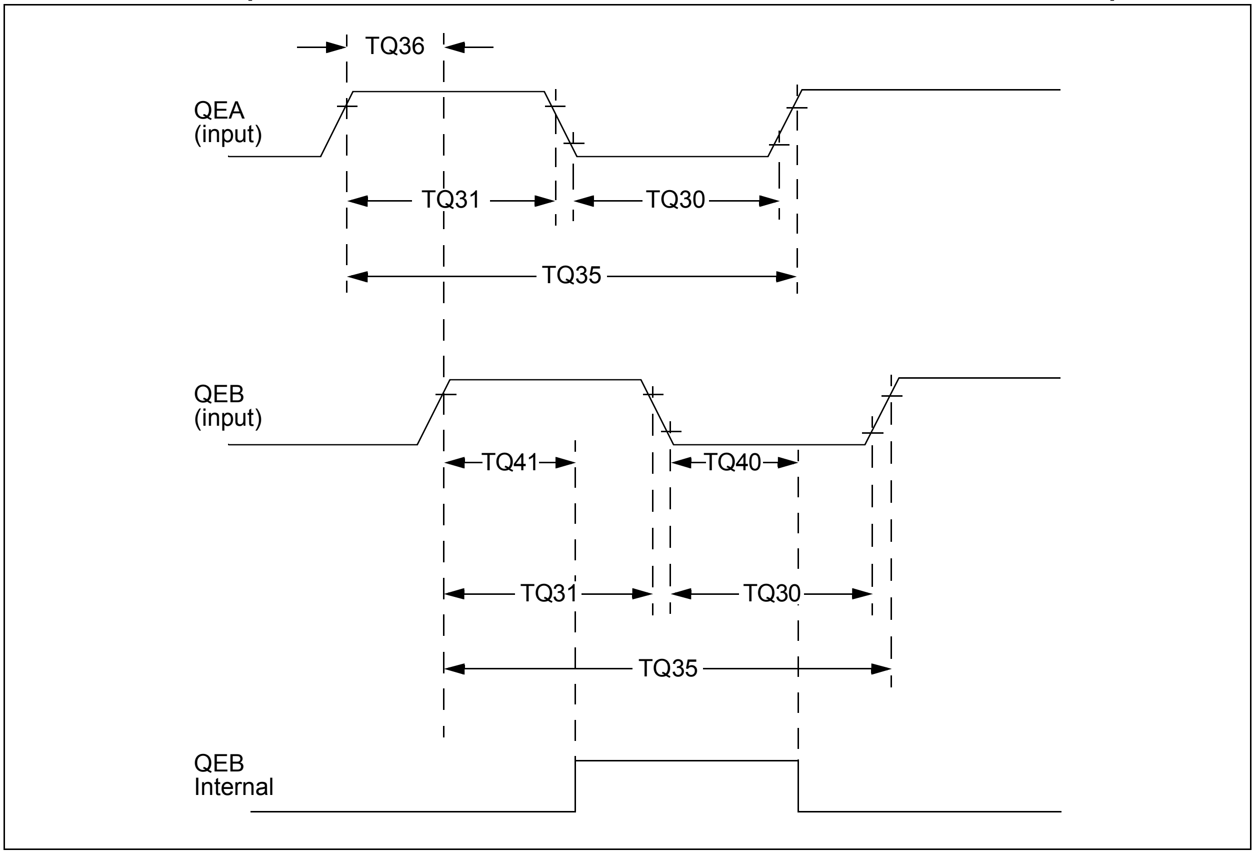

TABLE 30-31: QUADRATURE DECODER TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
TQ30	TQUL	Quadrature Input Low Time	6 TCY	—	ns	
TQ31	TQUH	Quadrature Input High Time	6 TCY	—	ns	
TQ35	TQUIN	Quadrature Input Period	12 TCY	—	ns	
TQ36	TQUP	Quadrature Phase Period	3 TCY	—	ns	
TQ40	TQUFL	Filter Time to Recognize Low, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 3)**
TQ41	TQUFH	Filter Time to Recognize High, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 3)**

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: N = Index Channel Digital Filter Clock Divide Select bits. Refer to **"Quadrature Encoder Interface (QEI)"** (DS70601) in the "*dsPIC33/PIC24 Family Reference Manual*". Please see the Microchip web site for the latest family reference manual sections.

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FIGURE 30-13: QEI MODULE INDEX PULSE TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

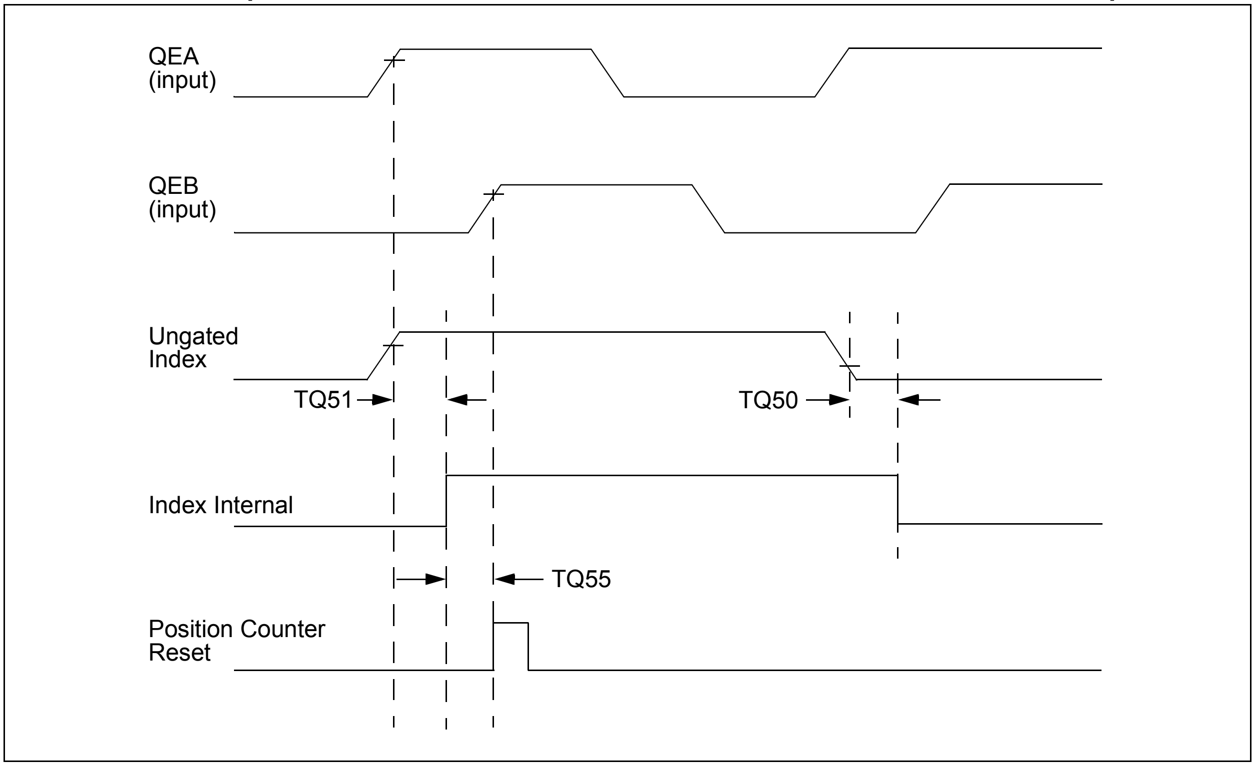


TABLE 30-32: QEI INDEX PULSE TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Max.**	**Units**	**Conditions**
TQ50	TqiL	Filter Time to Recognize Low, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ51	TqiH	Filter Time to Recognize High, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ55	Tqidxr	Index Pulse Recognized to Position Counter Reset (ungated index)	3 TCY	—	ns	

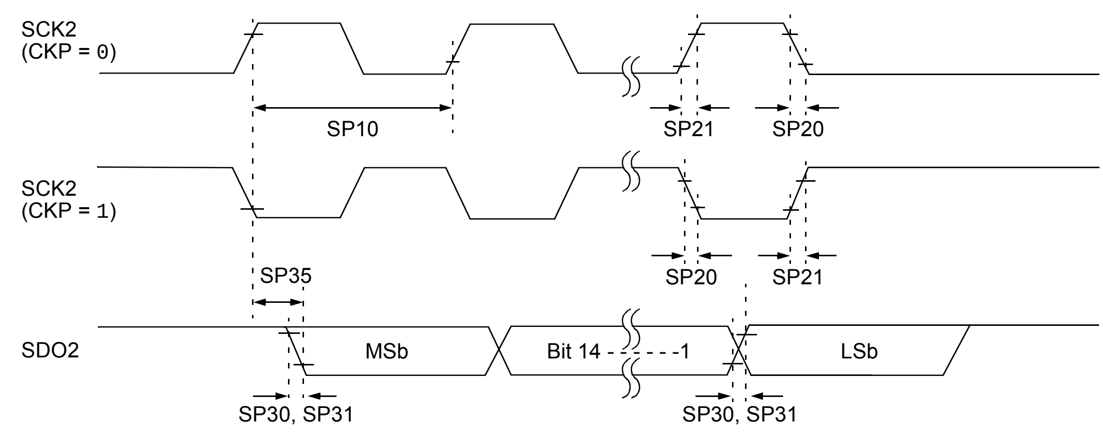
Note 1: These parameters are characterized but not tested in manufacturing.

2: Alignment of index pulses to QEA and QEB is shown for position counter Reset timing only. Shown for forward direction only (QEA leads QEB). Same timing applies for reverse direction (QEA lags QEB) but index pulse recognition occurs on the falling edge.

TABLE 30-33: SPI2 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 30-33	—	—	0,1	0,1	0,1
9 MHz	—	Table 30-34	—	1	0,1	1
9 MHz	—	Table 30-35	—	0	0,1	1
15 MHz	—	—	Table 30-36	1	0	0
11 MHz	—	—	Table 30-37	1	1	0
15 MHz	—	—	Table 30-38	0	1	0
11 MHz	—	—	Table 30-39	0	0	0

FIGURE 30-14: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

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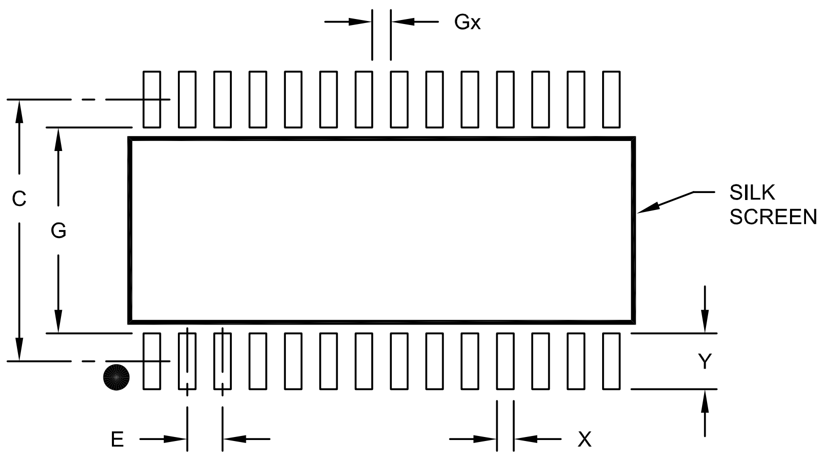
28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

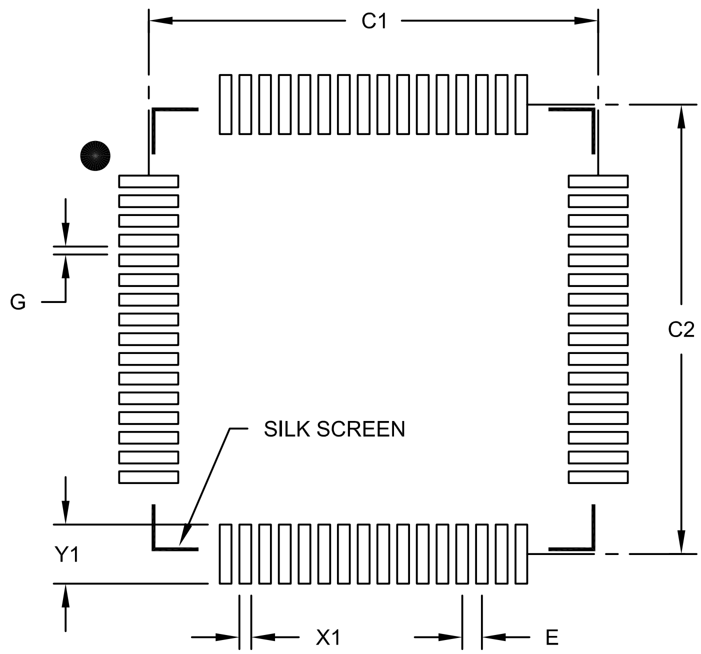
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

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TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"	Updated the High-Speed PWM Module Register Interconnection Diagram (see Figure 16-2). Added the TRGCONx and TRIGx registers (see Register 16-12 and Register 16-14, respectively).
Section 21.0 "Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)"	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 22.0 "Charge Time Measurement Unit (CTMU)"	Updated the IRNG<1:0> bit value definitions and added Note 2 in the CTMU Current Control Register (see Register 22-3).
Section 25.0 "Op amp/ Comparator Module"	Updated the Op amp/Comparator I/O Operating Modes Diagram (see Figure 25-1). Updated the User-programmable Blanking Function Block Diagram (see Figure 25-3). Updated the Digital Filter Interconnect Block Diagram (see Figure 25-4). Added **Section 25.1 "Op amp Application Considerations"**. Added Note 2 to the Comparator Control Register (see Register 25-2). Updated the bit definitions in the Comparator Mask Gating Control Register (see Register 25-5).
Section 27.0 "Special Features"	Updated the FICD Configuration Register, updated Note 1, and added Note 3 in the Configuration Byte Register Map (see Table 27-1). Added **Section 27.2 "User ID Words"**.
Section 30.0 "Electrical Characteristics"	Updated the following Absolute Maximum Ratings: • Maximum current out of VSS pin • Maximum current into VDD pin Added Note 1 to the Operating MIPS vs. Voltage (see Table 30-1). Updated all Idle Current (IIDLE) Typical and Maximum DC Characteristics values (see Table 30-7). Updated all Doze Current (IDOZE) Typical and Maximum DC Characteristics values (see Table 30-9). Added Note 2, removed Parameter CM24, updated the Typical values Parameters CM10, CM20, CM21, CM32, CM41, CM44, and CM45, and updated the Minimum values for CM40 and CM41, and the Maximum value for CM40 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Updated Note 2 and the Typical value for Parameter VR310 in the Op amp/ Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Note 1, removed Parameter VRD312, and added Parameter VRD314 to the Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated the Minimum, Typical, and Maximum values for Internal LPRC Accuracy (see Table 30-22). Updated the Minimum, Typical, and Maximum values for Parameter SY37 in the Reset, Watchdog Timer, Oscillator Start-up Timer, Power-up Timer Timing Requirements (see Table 30-24). The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-35)

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Revision D (December 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-3: MAJOR SECTION UPDATES

Section Name	Update Description
“16-bit Microcontrollers and Digital Signal Controllers (up to 512-Kbyte Flash and 48-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog”	Removed the Analog Comparators column and updated the Op amps/Comparators column in Table 1 and Table 2.
Section 21.0 “Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)”	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 30.0 “Electrical Characteristics”	Updated the V_{BOR} specifications and/or its related note in the following electrical characteristics tables: • Table 30-1 • Table 30-4 • Table 30-12 • Table 30-14 • Table 30-15 • Table 30-16 • Table 30-56 • Table 30-57 • Table 30-58 • Table 30-59 • Table 30-60

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